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EU RoHS Exemption(s)

PART INFORMATION

Mfg Item Number

AFT05MS004NT1

Mfg Item Name

SOT-89A

SUPPLIER Freescale Semiconductor Inc Company Name Company Unique ID 14-141-7928 2018-06-02 Response Date Response Document ID 007LK11060D027A1.5 Contact Name Freescale Semiconductor Inc Contact Title Product Technical Support **Contact Phone** 1-800-521-6274 Contact Email support@freescale.com **Authorized Representative** Daniel Binyon Representative Title **EPP Customer Response**

Representative Phone 512-895-3406
Representative Email eppanIst@freescale.com
URL for Additional Information www.freescale.com

DECLARATION

EU ROHS
Pb Free
Yes
HalogenFree
Yes
Plating Indicator

e3

MANUFACTURING Mfg Item Number AFT05MS004NT1 SOT-89A Mfg Item Name Version ALL Weight 0.050800 UoM Unit Volume EACH J-STD-020 MSL Rating Peak Processing Temperature 260 C Max Time at Peak Temperature 40 seconds Number of Processing Cycles 3



RoHS							
RoHS Directive	2011/65/EU						
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium						
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Su						
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above						
Supplier Acceptance	Accepted						
Signature	Daniel Binyon						
Exemption List Version	2012/51/EU						
List of Freescale Accepted Exemptions	6(a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight						
	6(b): Lead as an alloying element in aluminium containing up to 0.4% lead by weight						
	6(c): Copper alloy containing up to 4% lead by weight						
	7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)						
	7(b): Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications						
	7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound						
	7(c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher						
	7(c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC						
	7(c)-IV: Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors						
	15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages						



Homogeneous Material	Weight				SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Lead Frame Plating	0.0002					g				
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1	0.00000004	g	200	0.02	0	0
Lead Frame Plating		Metals	Tin, metal	7440-31-5	0.00019996	g	999800	99.98	3936	0.3936
Bonding Wire	0.0001					g				
Bonding Wire		Metals	Gold, metal	7440-57-5	0.0001	g	1000000	100	1968	0.1968
Copper Lead Frame	0.0245					g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8	0.02361689	g	963955	96.3955	464911	46.4911
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0	0.00002021	g	825	0.0825	397	0.0397
Copper Lead Frame		Metals	Iron, metal	7439-89-6	0.00057575	g	23500	2.35	11333	1.1333
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1	0.00000417	g	170	0.017	82	0.0082
Copper Lead Frame		Metals	Silver, metal	7440-22-4	0.000245	g	10000	1	4822	0.4822
Copper Lead Frame		Metals	Tin, metal	7440-31-5	0.00000735	g	300	0.03	144	0.0144
Copper Lead Frame		Metals	Zinc, metal	7440-66-6	0.00003063	g	1250	0.125	602	0.0602
Epoxy Die Attach	0.0002					g				
Epoxy Die Attach		Metals	Silver, metal	7440-22-4	0.00016108	g	805406	80.5406	3170	0.317
Epoxy Die Attach		Solvents, additives, and other materials	Proprietary Material-Other miscellaneous substances.		0.00000649	g	32432	3.2432	127	0.0127
Epoxy Die Attach		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resin	s -	0.00003243	g	162162	16.2162	638	0.0638
Die Encapsulant	0.0257					g				
Die Encapsulant		Plastics/polymers	Poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2	0.0003855	g	15000	1.5	7588	0.7588
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.0000771	g	3000	0.3	1517	0.1517
Die Encapsulant		Plastics/polymers	Proprietary Material-Other phenolic resins		0.001285	g	50000	5	25295	2.5295
Die Encapsulant		Glass	Silica, vitreous	60676-86-0	0.0226674	g	882000	88.2	446208	44.6208
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resin	s -	0.001285	g	50000	5	25295	2.5295
Silicon Semiconductor Die	0.0001					g				
Silicon Semiconductor Die		Metals	Gold, metal	7440-57-5	0.00000102	g	10200	1.02	20	0.002
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-	0.00000198	g	19796	1.9796	38	0.0038
Silicon Semiconductor Die		Glass	Silicon, doped	-	0.000097	g	970004	97.0004	1909	0.1909



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